

■ Application

Control equipment maintaining temperature from low to high in the chuck and wafer in the semiconductor test process.

■ Applied fields

EDS(Probe Test)



■ General Features

- ▶ Quick conversion from hot to cool processes
- ▶ Reliable application program at low temperature
- ▶ Variable type of cooling load adoption
- ▶ Quick stabilization time
- ▶ Chuck that minimized cooling time
- ▶ Use of a compressor, which is operable from low to high temperature.

■ Utility Requirements

Item	Specification single
Dimension	550(W)×980(D)×1550(H)
Temperature Range	1CH : -45°C ~ +150°C
Cooling Capacity	1CH : 2500 watts at -60 °C
Coolant Flow Rate	5LPM
Coolant Type	HFE-7200
Electrical Spec	208V, 3P, 4W, 30A
Temperature Accuracy	±0.1 °C